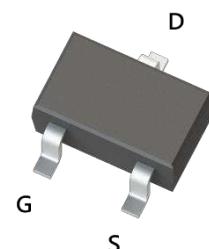


N-Channel Enhancement Mode MOSFET

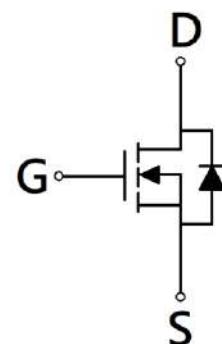
Features:

- Low On Resistance
- Low Gate Charge
- Fast Switching Characteristic

SOT-323



BV _{DSS}	20V
I _D @V _{GS} =4.5V, T _A =25°C	2.5A
R _{DS(ON)} typ. @ V _{GS} =4.5V, I _D =2A	50mΩ
R _{DS(ON)} typ. @ V _{GS} =2.5V, I _D =1A	60mΩ



G : Gate S : Source D : Drain

Ordering Information

Device	Package	Shipping
KWN2302	SOT-323 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 8	
Continuous Drain Current @ $V_{GS}=4.5\text{V}$, $T_A=25^\circ\text{C}$	I_D	2.5	A
Continuous Drain Current @ $V_{GS}=4.5\text{V}$, $T_A=70^\circ\text{C}$		2	
Pulsed Drain Current		10	
Continuous Body Diode Forward Current @ $T_A=25^\circ\text{C}$	I_S	0.55	
Total Power Dissipation	P_D	0.67	W
$T_A=70^\circ\text{C}$		0.43	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55~+150	$^\circ\text{C}$

Thermal Data

Parameter	Symbol	Steady State	Unit
Thermal Resistance, Junction-to-ambient	$R_{\theta JA}$	185	$^\circ\text{C/W}$

Note:

*a. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR -4 board with 2 oz. copper, in a still air environment with $T_A=25^\circ\text{C}$. The power dissipation P_D is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.

*b. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ\text{C}$. Ratings are based on low frequency and low duty cycles to keep initial $T_J=25^\circ\text{C}$.

Electrical Characteristics ($T_A=25^\circ C$, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions	
Static						
BV _{DSS}	20	-	-	V	V _{GS} =0V, I _D =250μA	
V _{GS(th)}	0.4	-	1.2		V _{DS} =V _{GS} , I _D =250μA	
G _{FS}	-	7	-	S	V _{DS} =5V, I _D =3A	
I _{GSS}	-	-	±100	nA	V _{GS} =±8V, V _{DS} =0V	
I _{DSS}	-	-	1	μA	V _{DS} =16V, V _{GS} =0V	
R _{DSS(ON)}	-	50	66	mΩ	V _{GS} =4.5V, I _D =2A	
	-	60	85		V _{GS} =2.5V, I _D =1A	
Dynamic						
C _{iss}	-	470	-	pF	V _{DS} =10V, V _{GS} =0V, f=1MHz	
C _{oss}	-	65	-			
C _{rss}	-	60	-	nC	V _{DS} =10V, I _D =3A, V _{GS} =4.5V	
R _g	-	1.2	-			
Q _g *1, 2	-	6.4	-	ns	V _{DS} =10V, I _D =3A, V _{GS} =5V, R _{GS} =6Ω	
Q _{gs} *1, 2	-	0.7	-			
Q _{gd} *1, 2	-	1.7	-	ns	V _{DS} =10V, I _D =3A, V _{GS} =5V, R _{GS} =6Ω	
t _{d(ON)} *1, 2	-	4.5	-			
t _r *1, 2	-	14	-	ns	V _{DS} =10V, I _D =3A, V _{GS} =5V, R _{GS} =6Ω	
t _{d(OFF)} *1, 2	-	30	-			
t _f *1, 2	-	8.5	-			
Source-Drain Diode						
V _{SD} *1	-	0.89	1.2	V	I _s =3A, V _{GS} =0V	
tr	-	6	-	ns	I _F =3A, dI _F /dt=100A/μs	
Q _{rr}	-	2	-			

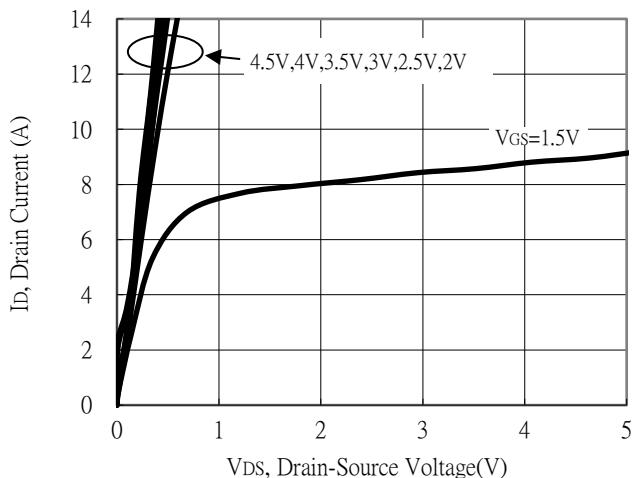
Note:

*1. Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

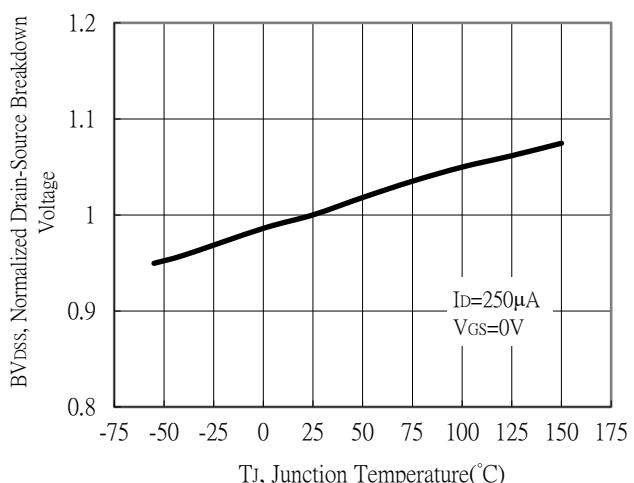
*2. Independent of operating temperature

Typical Characteristics

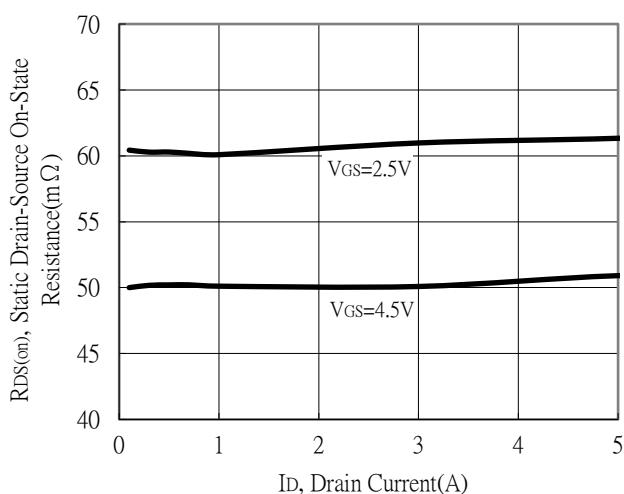
Typical Output Characteristics



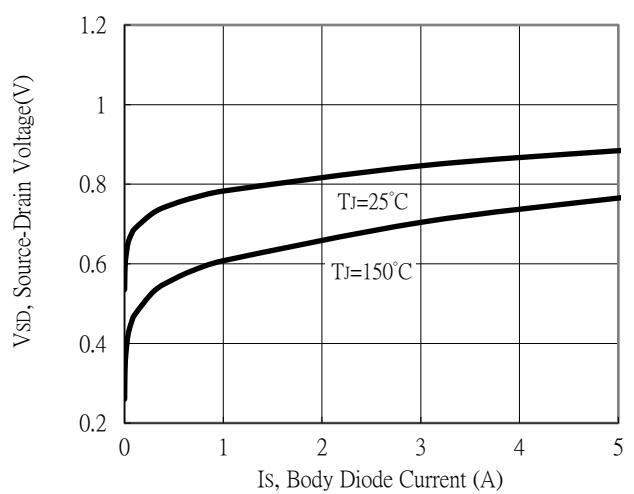
Breakdown Voltage vs Ambient Temperature



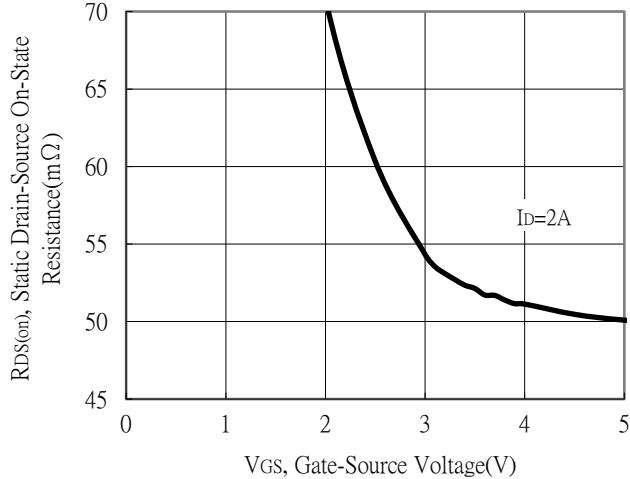
Static Drain-Source On-State resistance vs Drain Current



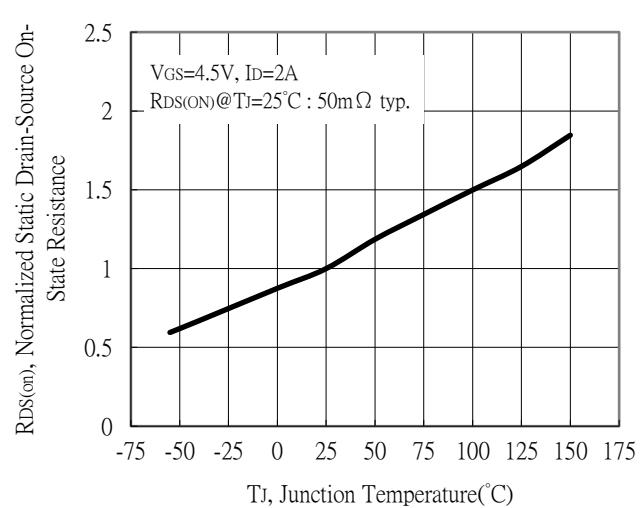
Body Diode Current vs Source-Drain Voltage



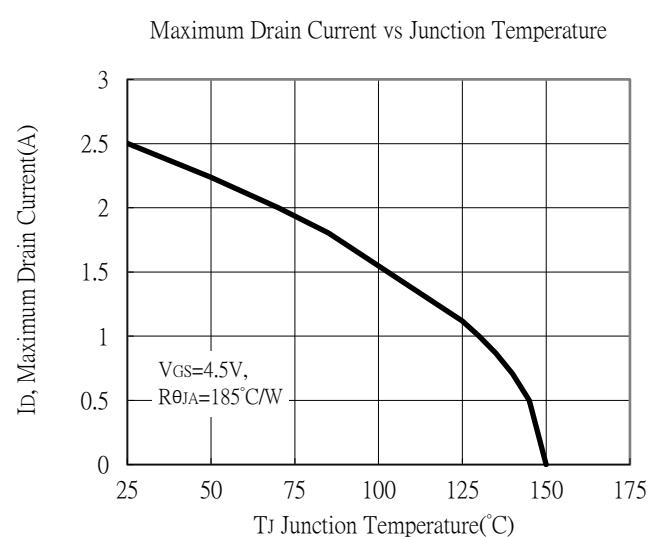
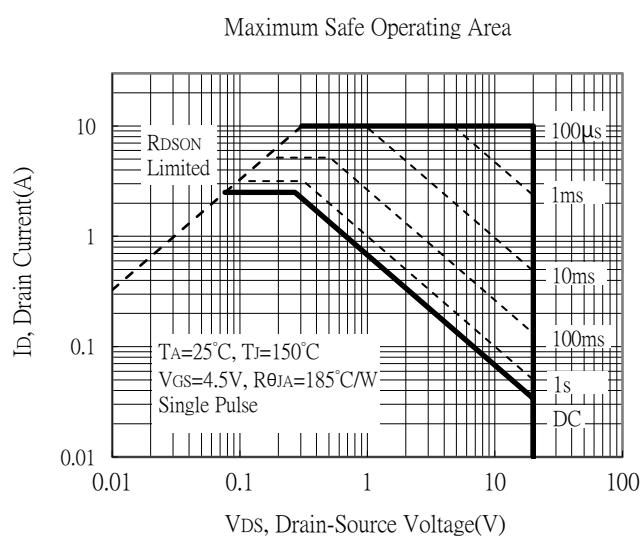
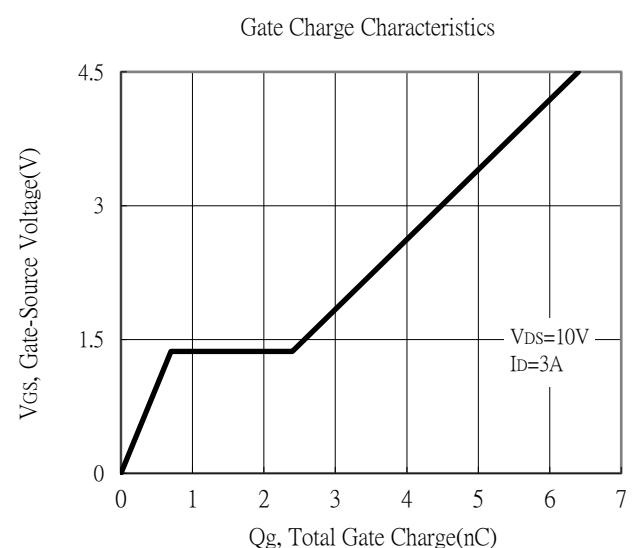
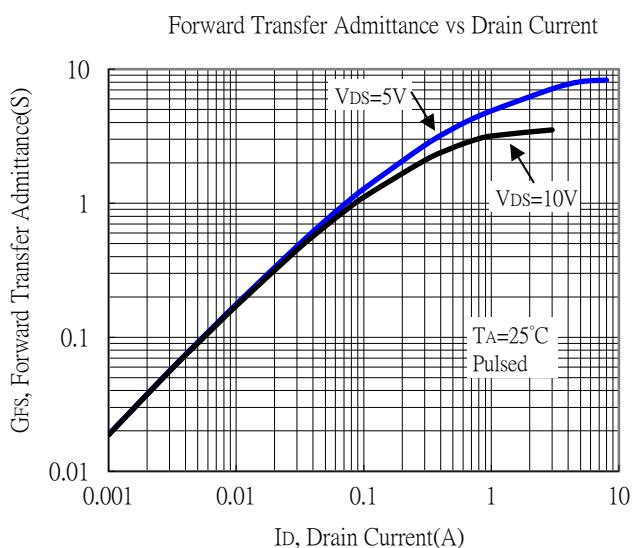
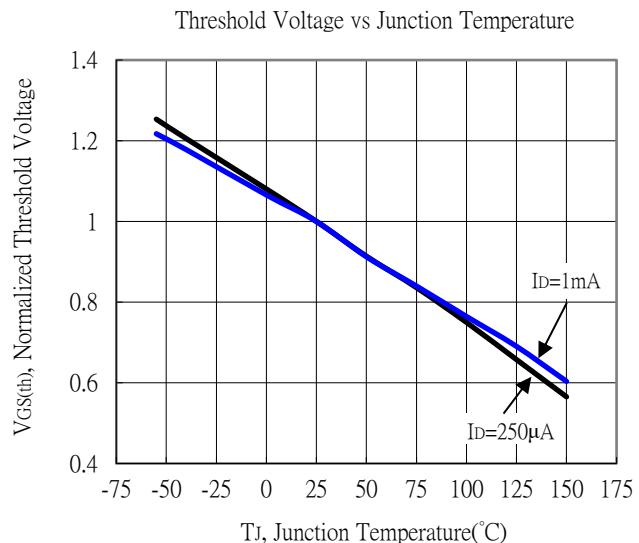
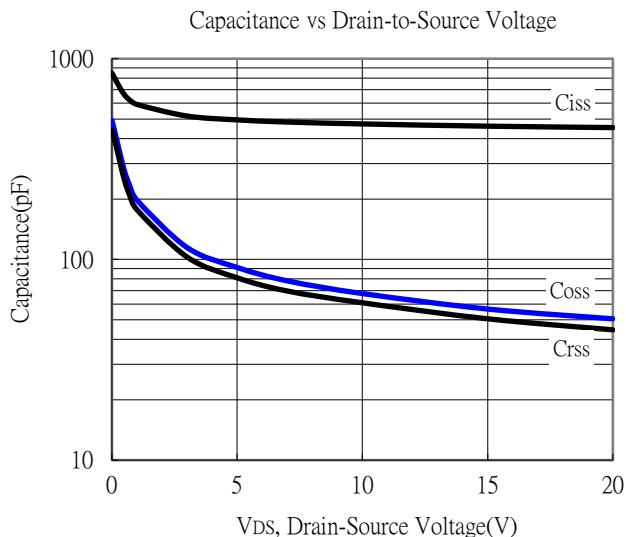
Static Drain-Source On-State Resistance vs Gate-Source Voltage



Drain-Source On-State Resistance vs Junction Temperature

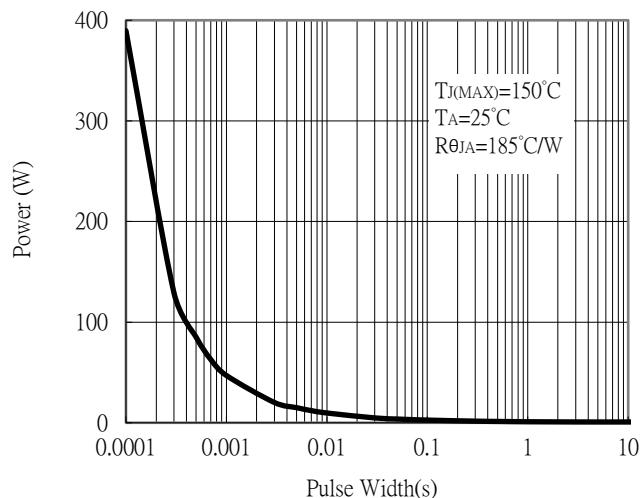


Typical Characteristics (Cont.)

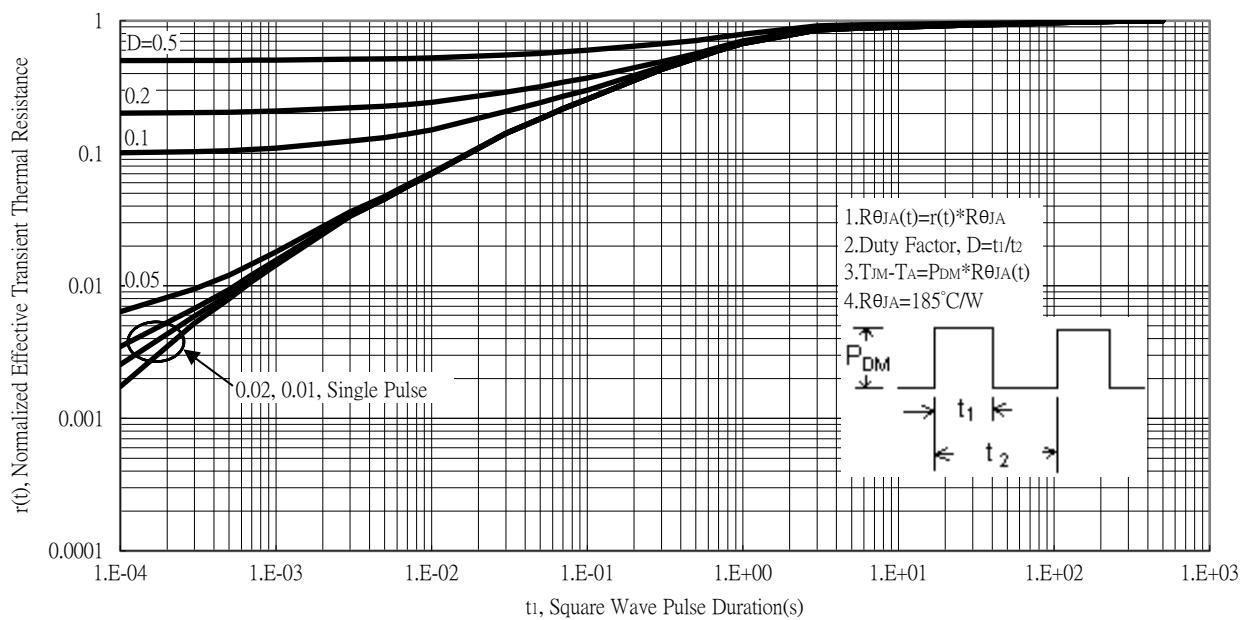


Typical Characteristics (Cont.)

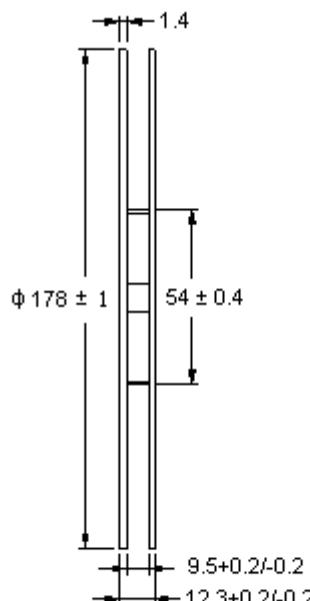
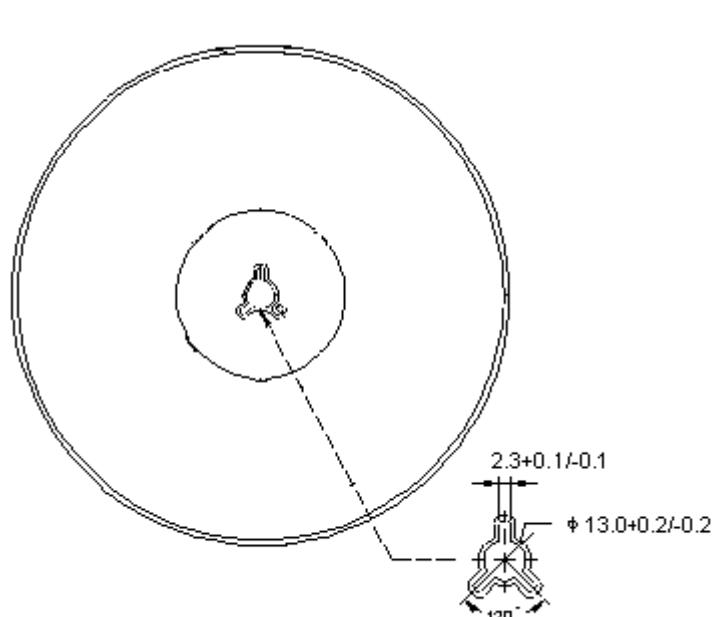
Single Pulse Power Rating, Junction to Ambient



Transient Thermal Response Curves

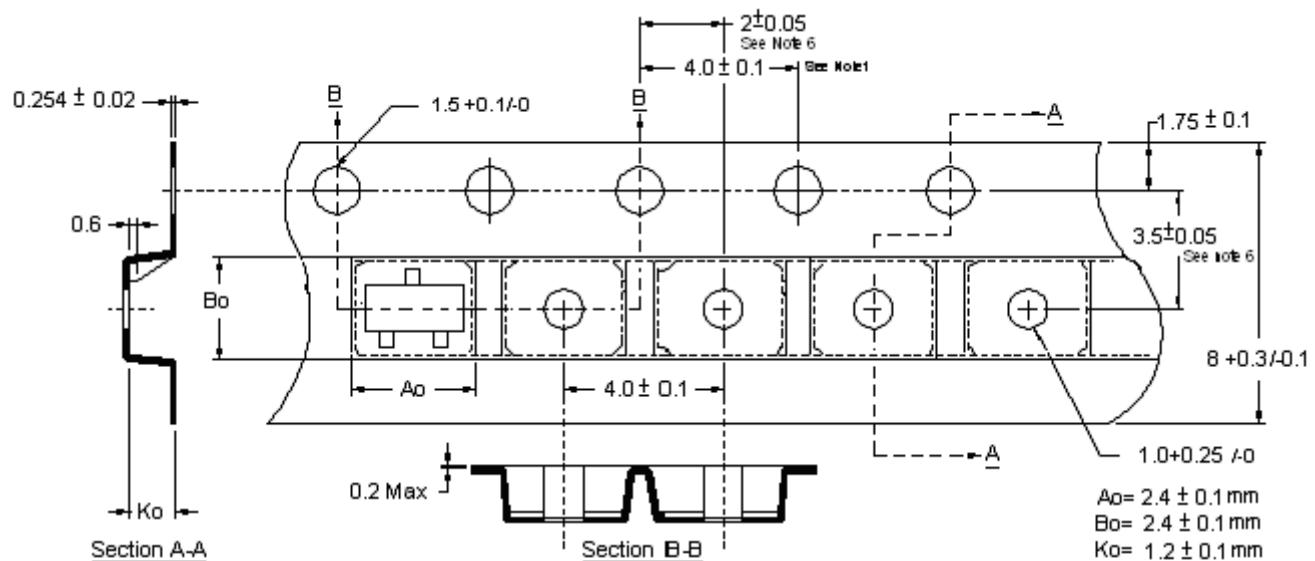


Reel Dimension



Unit: millimeter

Carrier Tape Dimension

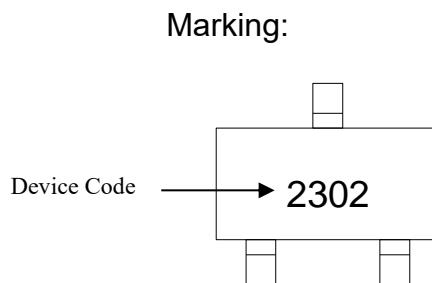
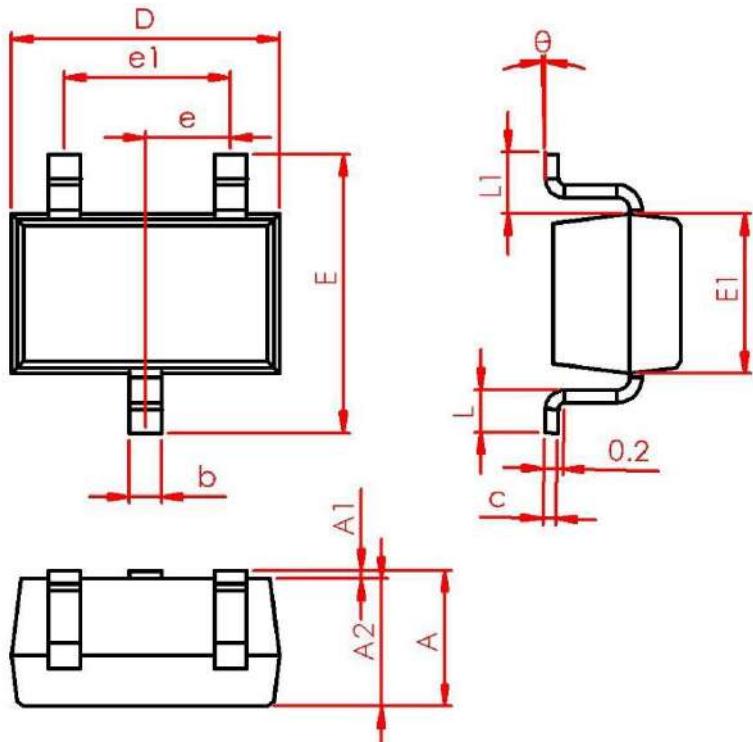


Notes:

1. 10 sprocket hole pitch cumulative tolerance ± 0.2 .
2. Camber not to exceed 1mm in 100mm.
3. Material : Conductive black polystyrene.
4. A_o & B_o measured on a plane 0.3mm above the bottom of the pocket.
5. K_o measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Unit : millimeter

SOT-323 Dimension



Style: Pin 1.Gate 2.Source 3.Drain

3-Lead SOT-323 Plastic Surface Mounted Package

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.035	0.043	0.900	1.100	E1	0.045	0.053	1.150	1.350
A1	0.000	0.004	0.000	0.100	e	0.026 TYP		0.650 TYP	
A2	0.035	0.039	0.900	1.000	e1	0.047	0.055	1.200	1.400
b	0.008	0.016	0.200	0.400	L	0.010	0.018	0.260	0.460
c	0.003	0.006	0.080	0.150	L1	0.021 REF		0.525 REF	
D	0.079	0.087	2.000	2.200	θ	0°	8°	0°	8°
E	0.085	0.096	2.150	2.450					